**PATENT ASSIGNMENT**

Electronic Version v1.1  
Stylesheet Version v1.1

### SUBMISSION TYPE: NEW ASSIGNMENT

### NATURE OF CONVEYANCE: ASSIGNMENT

#### CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>Satoshi EBATO</td>
<td>02/05/2008</td>
</tr>
<tr>
<td>Kenji YOSHIDA</td>
<td>02/08/2008</td>
</tr>
<tr>
<td>Tatsuhi TABUCHI</td>
<td>02/08/2008</td>
</tr>
<tr>
<td>Kou KOBAYASHI</td>
<td>02/08/2008</td>
</tr>
<tr>
<td>Yoshiito OKIZAKI</td>
<td>02/08/2008</td>
</tr>
<tr>
<td>Shigeru MASUDA</td>
<td>01/23/2008</td>
</tr>
</tbody>
</table>

#### RECEIVING PARTY DATA

- Name: SONY CORPORATION  
- Street Address: 1-7-1 Konan, Minato-ku  
- City: Tokyo  
- State/Country: JAPAN  
- Postal Code: 108-0075

**PROPERTY NUMBERS Total: 1**

<table>
<thead>
<tr>
<th>Property Type</th>
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<tbody>
<tr>
<td>Application Number</td>
<td>12035831</td>
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</table>

#### CORRESPONDENCE DATA

- Fax Number: (703)413-2220  
- Correspondence will be sent via US Mail when the fax attempt is unsuccessful.  
- Phone: (703) 413-3000  
- Email: iahmadi@oblon.com  
- Correspondent Name: Oblon, Spivak, et al.  
- Address Line 1: 1940 Duke Street  
- Address Line 4: Alexandria, VIRGINIA 22314

**ATTORNEY DOCKET NUMBER:** 322542US8

**NAME OF SUBMITTER:** Ismail Ahmadi
ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
INFORMATION PROCESSING APPARATUS, IMAGING APPARATUS, IMAGE DISPLAY CONTROL METHOD AND
COMPUTER PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name
and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku,
Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention,
said application disclosing the invention and in, and under any Letters Patent or similar legal protection which may be granted
thereof in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration,
the receipt and sufficiency of which are here acknowledged, I, as a sole or joint inventor as indicated below, b
hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and
interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters
Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority
rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention
Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America
adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of
patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the
said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of
ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me
and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention,
applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful
papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or
reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and
prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents
relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and
accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which
would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of
this application in the spaces that follow: Serial Number: ___________________, Filing Date: ___________________.

This assignment executed on the dates indicated below.

Satoshi EBATO
Name of first or sole inventor
Tokyo, Japan
Residence of first or sole inventor

Signature of first or sole inventor

February 5, 2008
Execution date of U.S. Patent Application

February 5, 2008
Date of this assignment
Kenji YOSHIDA
Name of second inventor
Kanagawa, Japan
Residence of second inventor
Kenji Yoshida
Signature of second inventor
Execution date of U.S. Patent Application
February 8, 2008
Date of this assignment

Tatsuhito TABUCHI
Name of third inventor
Tokyo, Japan
Residence of third inventor
Tatsuhito Tabuchi
Signature of third inventor
February 8, 2008
Date of this assignment

Kou KOBAYASHI
Name of fourth inventor
Tokyo, Japan
Residence of fourth inventor
Kou Kobayashi
Signature of fourth inventor
February 8, 2008
Date of this assignment

Yoshiiito OKIZAKI
Name of fifth inventor
Tokyo, Japan
Residence of fifth inventor
Yoshiiito Okizaki
Signature of fifth inventor
February 8, 2008
Date of this assignment
Shigeru MASUDA

Name of sixth inventor

Kanagawa, Japan

Residence of sixth inventor

Shigeru Masuda

Signature of sixth inventor

January 23, 2008

Execution date of U.S. Patent Application

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment